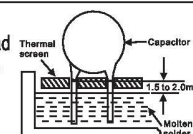
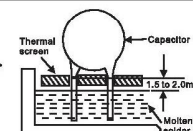


Continued from the preceding page.

No.	Item	Specifications	Testing Method	
8	Solderability of Leads	Lead wire shall be soldered with uniformly coated on the axial direction over 3/4 of the circumferential direction.	The lead wire of a capacitor should be dipped into molten solder for 2±0.5 sec. The depth of immersion is up to about 1.5 to 2.0mm from the root of lead wires. Temp. of solder: Lead Free Solder (Sn-3Ag-0.5Cu) 245±5°C H63 Eutectic Solder 235±5°C	
9	Soldering Effect (Non-Preheat)	Appearance	No marked defect.	
		Capacitance Change	Within ±10%	
		I. R.	1000MΩ min.	
		Dielectric Strength	Per Item 6.	
10	Soldering Effect (On-Preheat)	Appearance	No marked defect.	
		Capacitance Change	Within ±10%	
		I. R.	1000MΩ min.	
		Dielectric Strength	Per Item 6.	
11	Vibration Resistance	Appearance	No marked defect.	
		Capacitance	within the specified tolerance	
		tanδ or Q	Char.	Specifications
			C, L	Q ≥ 400+20C _R (C _R < 30pF) Q ≥ 1000 (C _R ≥ 30pF)
X, B, E	tanδ ≤ 0.025			
	F	tanδ ≤ 0.050		
12	Humidity (Under steady state)	Appearance	No marked defect.	
		Capacitance Change	C: Within ±2.5% L: Within ±5.0% X, B, E: Within ±10% F: Within ±15%	
		tanδ or Q	Char.	Specifications
			C, L	Q ≥ 275+5/2C _R (C _R < 30pF) Q ≥ 350 (C _R ≥ 30pF)
		X, B, E	tanδ ≤ 0.050	
F	tanδ ≤ 0.075			
I. R.	3000MΩ min.			
Dielectric Strength	Per Item 6.			



*1 "room condition" Temperature: 15 to 35°C, Relative humidity: 45 to 75%, Atmospheric pressure: 86

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